BGF104C

HSMMC Interface Filter and ESD Protection

RF & Protection Devices

Never stop thinking

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BGF104C

Revision History: 2009-11-12, V2.0

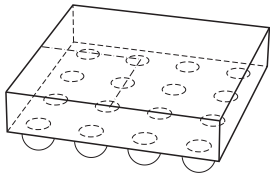
Previous Version: 2009-09-14, V1.0

Page	Subjects (major changes since last revision)
4	3D-figure of package updated
5	**Figure 2** updated
6	Footprint (**Figure 3**) added
6	Tape specification (**Figure 4**) added
all	Target status removed

BGF104C

Features

- ESD protection and filter for High Speed Multi Media Card interface
- ESD protection according to IEC61000-4-2 for ±15 kV contact discharge on external IOs
- 16 pin green wafer level package with SnAgCu solder balls
- RoHS and WEEE compliant package
- 500 µm solder ball pitch
- 300 µm solder ball diameter



WLP-16-3-N

RoHS

Description

BGF104C is an ESD protection and filter circuit for a high speed multi media card interface. External pins are protected against ESD pulses of ±15 kV contact discharge according to IEC61000-4-2. The wafer level package is a green leadfree package with a size of only 1.92 mm x 1.92 mm and a total height of 0.65 mm.

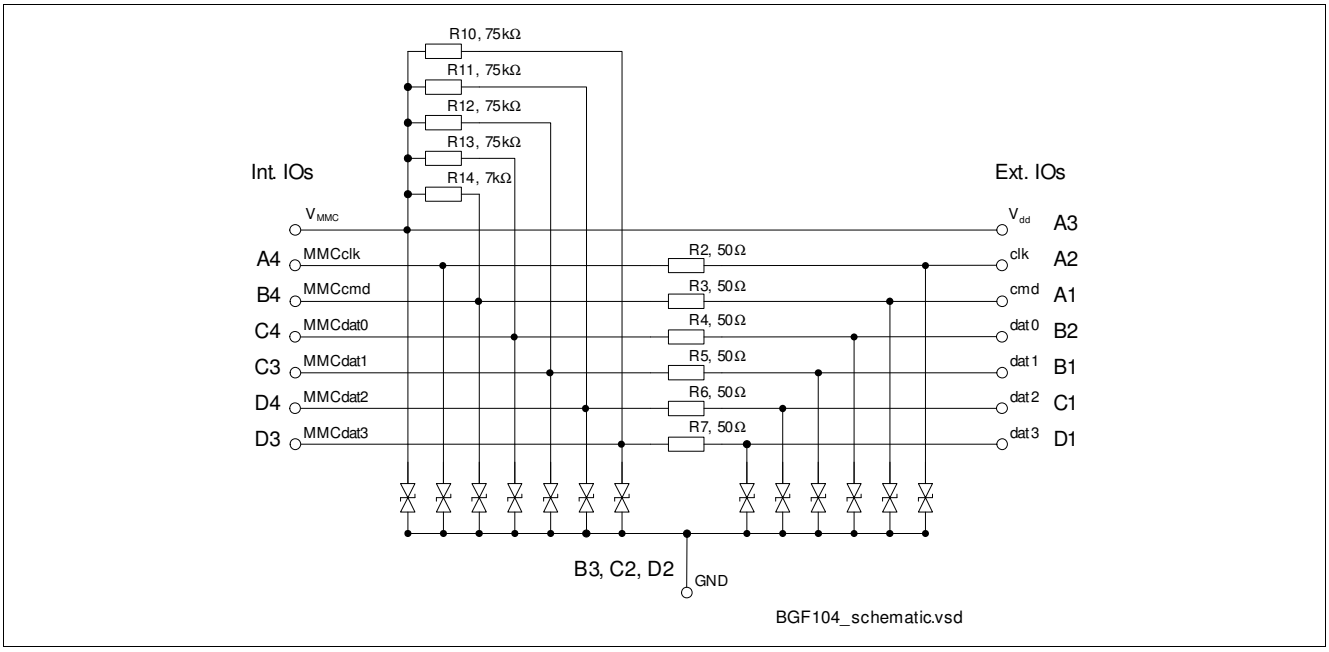


Figure 1 Schematic

Type	Package	Marking	Chip
BGF104C	WLP-16-3	4C	N0708

Table 1 Maximum Ratings

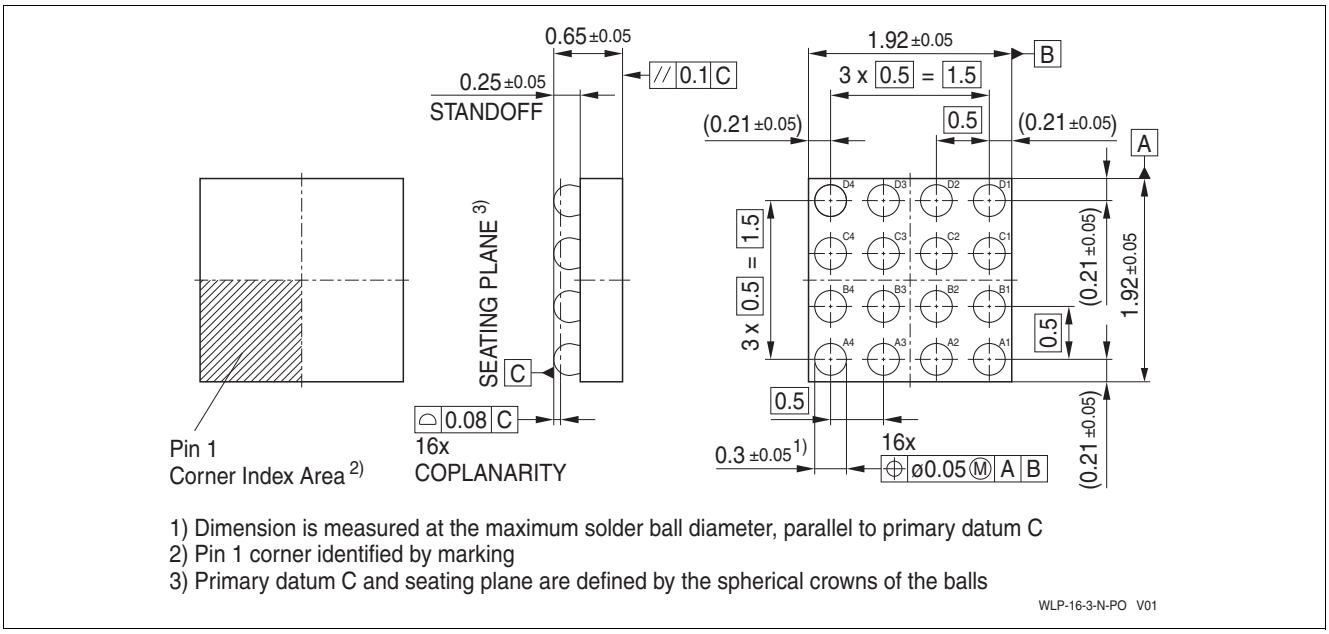
Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Voltage at all pins to GND	V_P	0	–	14	V	–
Operating temperature range	T_{OP}	-40	–	+85	°C	–
Storage temperature range	T_{STG}	-65	–	+150	°C	–
Electrostatic Discharge According to IEC61000-4-2						
Contact discharge external pins to GND (A1, A2, A3, B1, B2, C1, D1)	V_{ESD}	-15	–	15	kV	–
Contact discharge internal pins to GND (A4, B4,C3, C4, D3, D4)	V_{ESD}	-2	–	2	kV	–

Table 2 Electrical Characteristics[1)]

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Resistors R_2 ... R_7	$R_{2...7}$	40	50	60	Ω	–
Resistors R_{10} ... R_{13}	$R_{10...13}$	52.5	75	97.5	kΩ	–
Resistor R_{14}	R_{14}	4.9	7	9.1	kΩ	–
Line capacitance, each line to GND[2)]	C_T	–	16	20	pF	V = 0 V
Reverse current of ESD protection diodes I_R = 3 V I_R = 14 V	I_R	–	 5 0.1	 100 10	 nA µA	–

1) at T_A = 25 °C
2) Without line coupling by Resistors R_7 - R_{11}

Package Outlines



1) Dimension is measured at the maximum solder ball diameter, parallel to primary datum C
2) Pin 1 corner identified by marking
3) Primary datum C and seating plane are defined by the spherical crowns of the balls

WLP-16-3-N-PO V01

Figure 2 WLP-16-3 (dimensions in mm)

Footprint

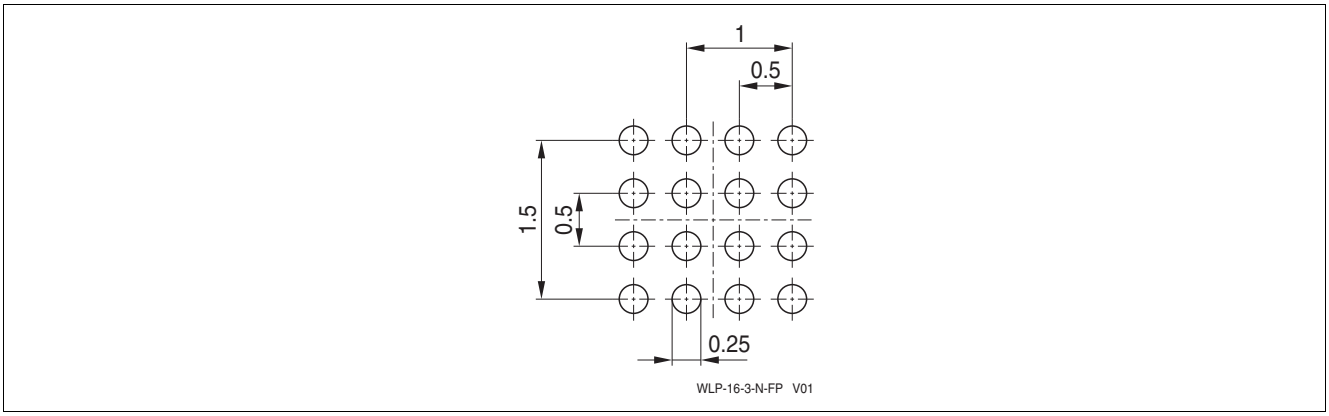


Figure 3 Footprint for WLP-16-3 (dimensions in mm)

Tape and reel specification

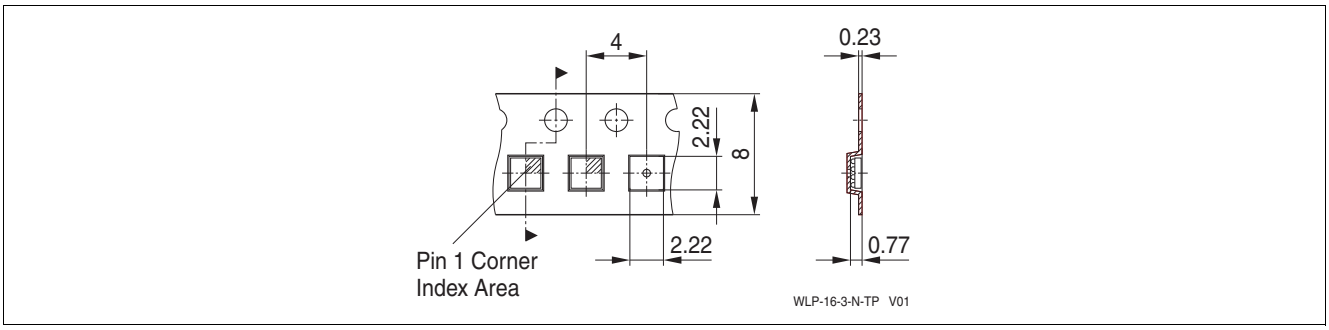


Figure 4 Tape for WLP-16-3 (dimensions in mm)

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